



Material Content Data Sheet



Sales Product Name				BTS50080-1TMC		Issued		14. September 2018	
MA#				MA001044082					
Package				PG-TO220-7-4		Weight*		1525.81 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	5.233	0.34	0.34	3430	3430	
chip_2	inorganic material	silicon	7440-21-3	1.157	0.08	0.08	759	759	
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		158		
	non noble metal	iron	7439-89-6	0.804	0.05		527		
	non noble metal	copper	7440-50-8	802.842	52.61	52.68	526172	526857	
	non noble metal	aluminium	7429-90-5	2.541	0.17	0.17	1665	1665	
wire	non noble metal	aluminium	7429-90-5	2.541	0.17	0.17	1665	1665	
encapsulation	organic material	carbon black	1333-86-4	8.854	0.58		5803		
	plastics	epoxy resin	-	97.389	6.38		63828		
	inorganic material	silicondioxide	60676-86-0	483.993	31.72	38.68	317203	386834	
leadfinish	non noble metal	tin	7440-31-5	12.090	0.79	0.79	7924	7924	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	141	142	
solder	non noble metal	tin	7440-31-5	0.079	0.01		52		
	noble metal	silver	7440-22-4	0.099	0.01		65		
	non noble metal	lead	7439-92-1	3.783	0.25	0.27	2479	2596	
glue	plastics	Polyimide	26023-21-2	0.143	0.01	0.01	93	93	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	iron	7439-89-6	0.106	0.01		70		
	non noble metal	copper	7440-50-8	106.210	6.96	6.97	69609	69700	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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